Eclipse XT
Highly Configurable Scalable Pick-and-Place Handler

Productivity
• Up to 13,000 UPH
• Parallelism x1 to x16
• Output bins: 3 auto, 3 manual
• 3x3 mm to 80x80 mm package handling
• Passive SLK and device kit compatible with competitors’
• Chamberless Tri-Temp; No LN2

Differentiation
• Ultra fast T-Core Active Thermal Control
• 800 W DUT power dissipation (with Tri-Temp option)
• Tight guard band for Start of Test (with load board/ socket thermal conditioning option)
• NIST traceable thermal calibration
• Configurable SLK x1 to x4 with multiple pitches (Tri-Temp only)
• Field upgradeable to Ambient/Hot ATC or Tri-Temp ATC (for passive configuration)
• Force convective and chiller based cooling system - high reliability

• Ambient to 130°C (Standard)
• Tri-temp range -55°C to +155°C
• Ultra fast T-Core Active Thermal Control

• Low to 800 W power applications
• OSAT friendly standard process flow and device kits compatible
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Specifications

Platform

Media
• JEDEC trays

Input and Sorts
• 3 - Automated sort bins
• 3 - Manual trays
• Continuous load/unload

Test Site
• x1 to x16 (x32 road map)

Plunge Force
• 250 Kg
• 500 Kg (optional)

Index Time*
• < 800 ms

Throughput*
• 13,000 UPH

Features and Options
• NVcore vision In-Socket part detection
• Vision 2DID, u2DID
• Auto Retest
• Manual RFID
• DUT rotation
• 500 Kgf socket force
• DOOP input shuttle
• Auto contactor cleaning

Temperature Range
• Passive: Ambient to 130°C (155°C option)
• Ambient/Hot ATC: Ambient to 130°C (155°C option)
• Tri-Temp ATC: -40°C to 130°C (-55°C to 155°C option)

Thermal (Base)*
• Best in class Active Thermal Control with 50+ patents
• +/- 1°C temperature accuracy at the thermal head
• Hot soak station (cold soak on thermal head)
• Power and DUT temperature feedback loop available
• NIST traceable thermal calibration
• Chamberless test site
• Temperature ramp up to 100°C per second at thermal head

T-Core Thermal Options
• Device power feedback loop
• Device diode temperature feedback loop
• Load board/socket thermal conditioning (LBC)
• Socket thermal conditioning (DTM)
• Liquid and mechanical thermal interface
• Force convective or HFE chiller based cooling system for ATC
• Highly configurable SLK x1 to x4 test parallelism in multiple x,y pitches

Tester Interface
• Load board compatibility: (X and Y pitch)
• Docking height 990 to 1,178 mm
• RS 232, GPIB and P849

ESD Control
• Decay: 1,000 V to 100 V in 10 s
• Balance: ± 30 V
• Enhanced Decay Option: 1,000 V to 100 V in 5 s

User Interface
• Windows-based

Power Requirements
• 200-230 VAC, 50/60Hz, Single Phase, 30 A
• Additional: 30 A with T-Core

Change Kit

Device Types
• QFP, TQFP, TSOP, SOIC, CSP, BGA, QFN, WLCSP and others
• OSAT kit-compatible
• Passive device kits and SLK’s compatible with competitors’

Package Size
• Minimum: 3 x 3 mm
• Maximum: 80 x 80 mm

Kit Changeover
• < 15 minutes typical

Contactors
• Cohu offers contact sockets for all package versions and application

OSAT-Compatible
• Reuse existing OSAT kits
• Reuse existing Passive kits and SLKs

Specifications subject to change without notice. For detailed performance specifications, please contact Cohu.